



# Internal H<sup>0</sup>/H<sup>-</sup> dump

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On behalf of EN/STI

Thanks to: A. Christov, S. Mathot, C. Pasquino, A. Patapenka

# Outline

- Loading cases
- Methods of fixation
- Space & layout
- FOMS
- Choice of material(s)
- Electrical behavior
- Preliminary analyses :
  - Instantaneous DT
  - Steady operation
  - Transient to steady operation
- Does the dump need active cooling ?
- Conclusions

# Loading cases

Table 1 - main machine parameters for  $H^0/H^-$  beam dump definition.

EDMS 963395

Ion species		$H^0/H^-$
Beam energy (kinetic)	MeV	160
Max. repetition rate	Hz	1.11
Max. Beam pulse length (useful beam)	$\mu s$	400
Injection turns		$4 \times 100$
Beam head/tail length	$\mu s$	<60/20
Peak LINAC current	mA	40
RFQ peak current	mA	70
Average LINAC current	mA	0.018
Max. beam power	kW	2.8
Max Nbr. of particles per beam pulse		$1.0 \times 10^{14}$

## Three loading case (following stripping efficiency):

- (1)  $e = 98\%$  (foil operational)
- (2)  $e = 90\%$  (foil degraded)
- (3)  $e = 0\%$  (foil accident)

## Operation:

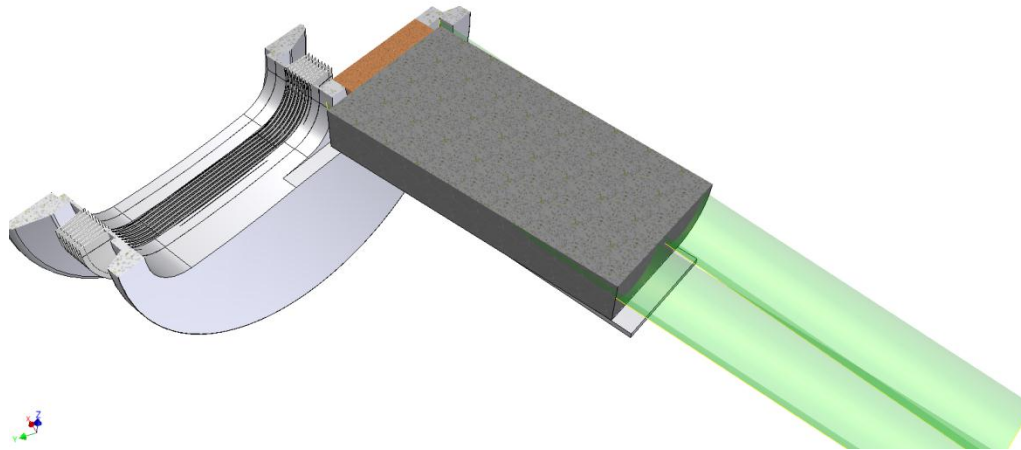
- > Steady-state, 2% all  $H^0$ , 0.8mA
- > Steady-state, 10% all  $H^0$ , 4mA, 8h max
- > Transient 1/4 Linac4 pulse, 40mA, 100%  $H^-$  (interlock after 1 pulse)

## 4/4 Linac4 Beam loading case (foil accident + distributor failure)

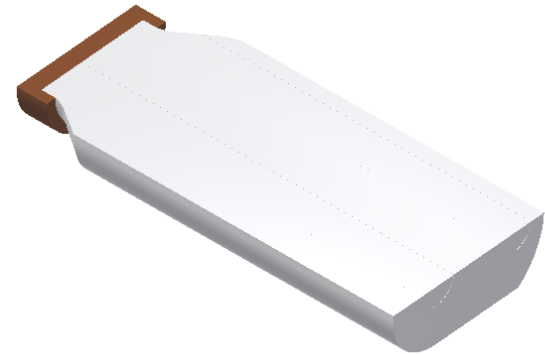
- > **not considered**

# Methods of fixation

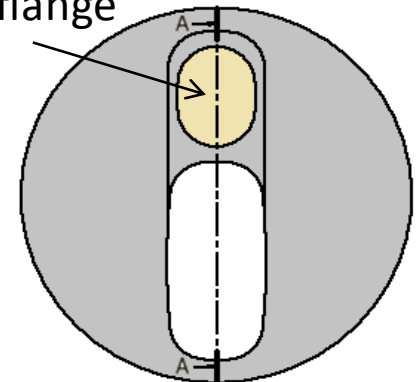
- ***Metallization + Brazing***



- ***Shrinking***



Copper part inserted  
into Steel flange

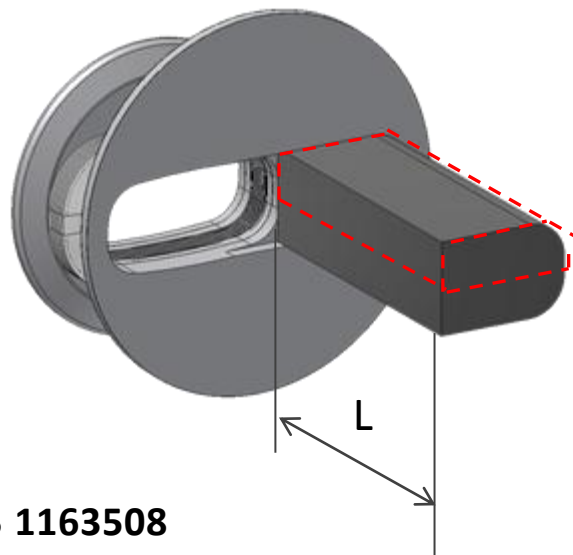


For both solution:

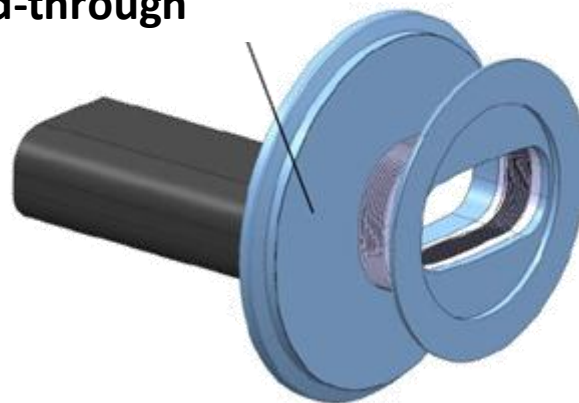
- Metallic part inserted into Steel flange

# Space & layout

Area to be modified for the cooling/bake-out of the dump, possibly **no feed-through**



EDMS 1163508



- The flange has to be adapted to the assembly / fixation / cooling needs of the dump
- The instrumentation has to be fixed on the dump (front face)
- The dump is one-piece with the flange (ALARA, quick exchange / disassembly)

# FOMS

**To be  
minimized**

- Thermal:  $FOM_1 = \frac{T_{100 \% beam}}{T_{service\ maxi.}} < 1$
- Structural:  $FOM_2 = \frac{Z * E(Pa) * \alpha(K^{-1})}{A * Yield(Pa) * Cp} < 1$
- RP (simplified):  $FOM_3 = Z \searrow$
- Vacuum:  $FOM_4 = porosity \searrow$

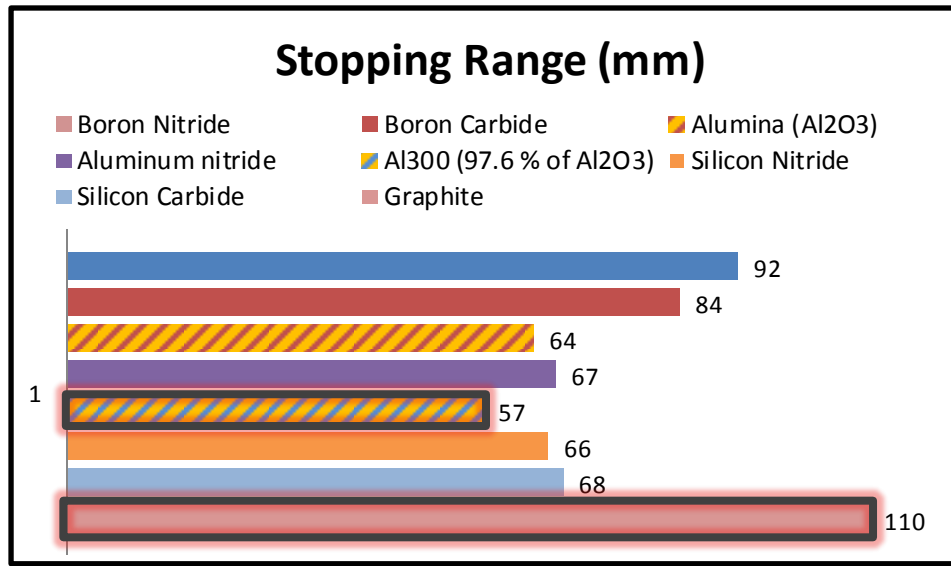
**ON/OFF**

- Electrical Conductivity:  $< \sigma_{Graphite}$  **but not too small**
- Weld-ability: depend on method of fixation



***Ceramic material (8 material identified)***

# Choice of material(s)

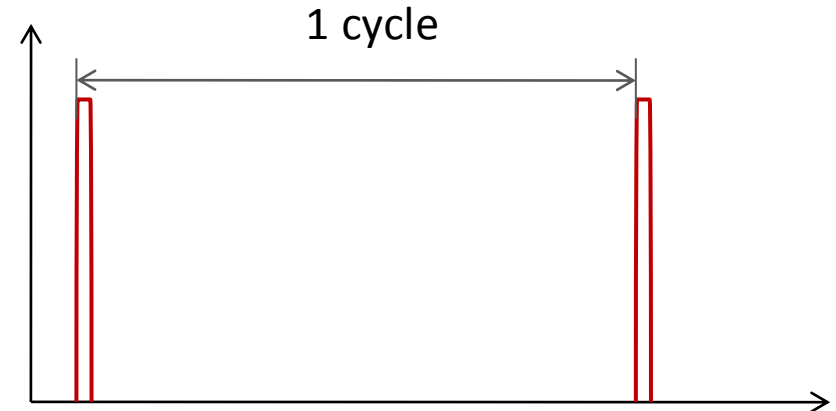


**Graphite:**  
 Good thermal behavior  
*BUT*  
 Vacuum pb + fixation pb

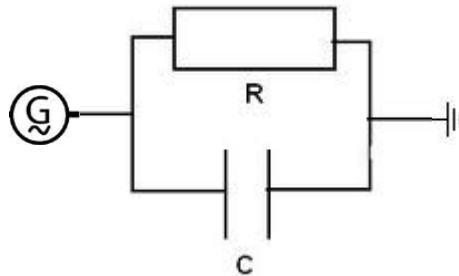
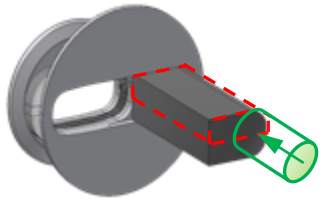
**Al300:**  
 Possible to be brazed to a metallic part + good thermal and structural behavior  
*BUT*  
 Bad Electrical behavior (risk of highly charging)

# Electrical behavior (1)

**Conservative approximated model to define the electrical behavior of material** → the full charge of the beam is deposited in the material during the charge.



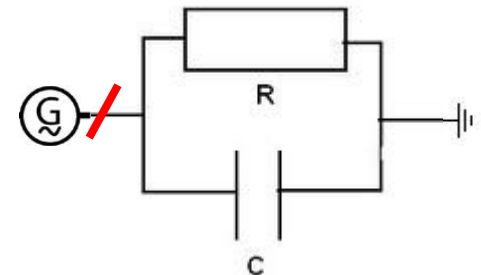
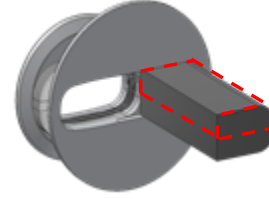
Beam → Charge: parallel RC model



$$V(t) = I_b(t) \cdot \left( \frac{C}{t} + \frac{1}{R} \right)^{-1}$$

$t = \text{pulse length}$

NO Beam → Discharge: series RC model



$$V(t) = V_C(t) = V_{initial} \cdot \exp\left(-\frac{t}{RC}\right)$$

$t = \text{cycle length}$



# Electrical behavior (2)

In reality, some charges escape from the dump while the “charging” phase  
 → Fluka simulation were done to assess the % of escaping charges.

	Graphite	Al300	SiC	
Total Charge, full beam (V)	1.07e-7	22500	1.98	← End of pulse
% escaping (Fluka)	5.23	0.28	0.79	
Charge accumulated (Fluka) (V)	1.01e-7	22400	1.96	← End of pulse
Charge after Discharge (V)	0	22200	0	← End of full cycle

At the end of the cycle, the accumulated charge should be *as low as possible* →  $FOM_5 = RC$

→ **Al300** cannot be used for the dump

- *does the chamber risk to be charged too?*

→ **SiC** is the current material choice

- *can be brazed to a metallic part (few companies contacted)*

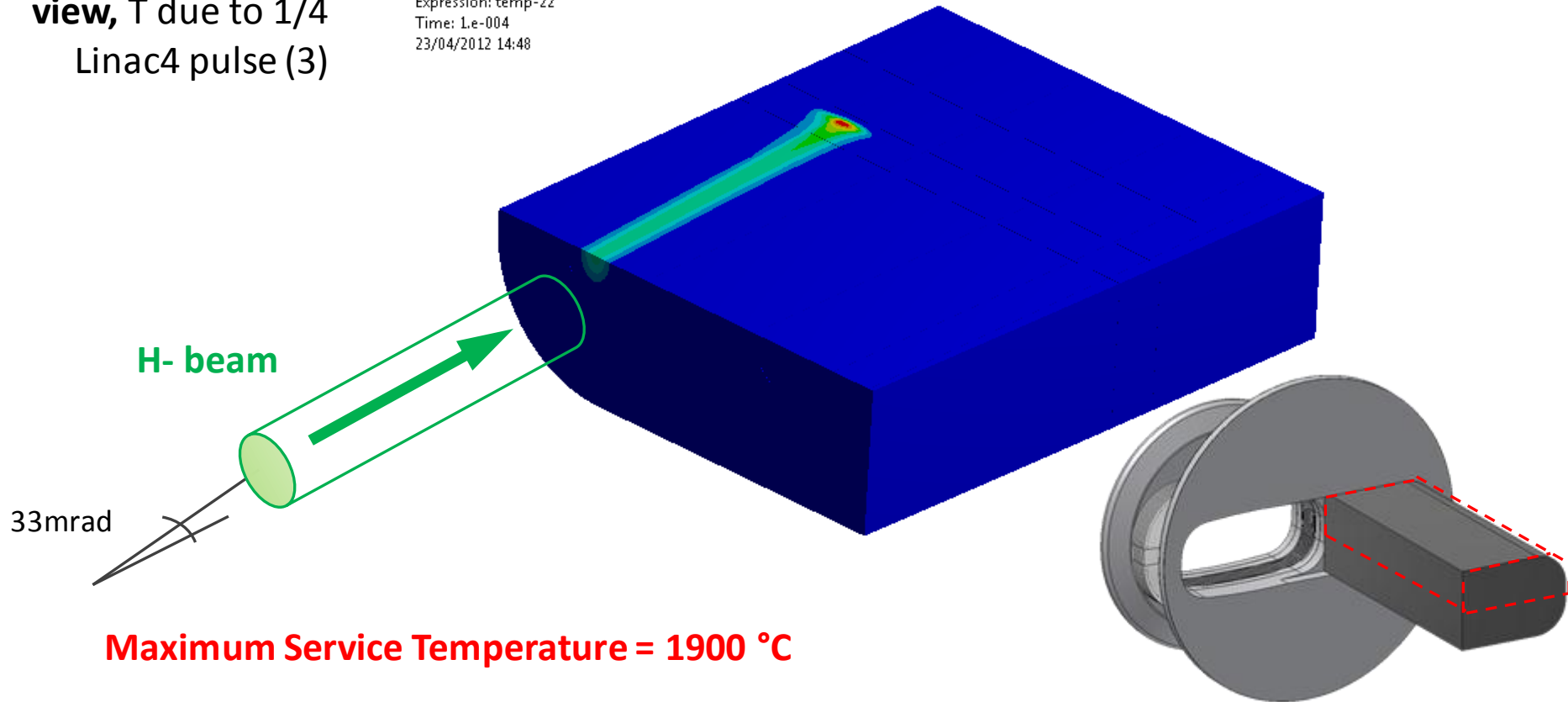
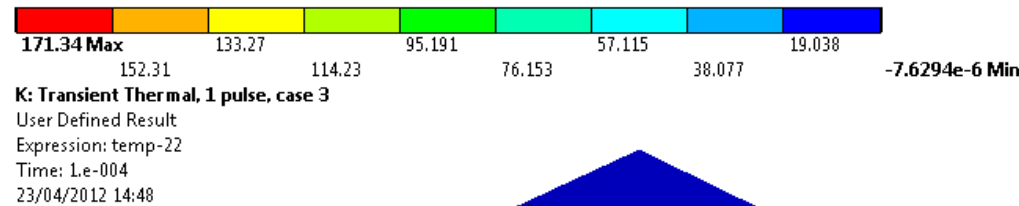
- *respect all FOMs*

Results for the loading case 2: 10 % of the beam, H0 beam, only **1 cycle** considered.

# Instantaneous $\Delta T$ – SiC

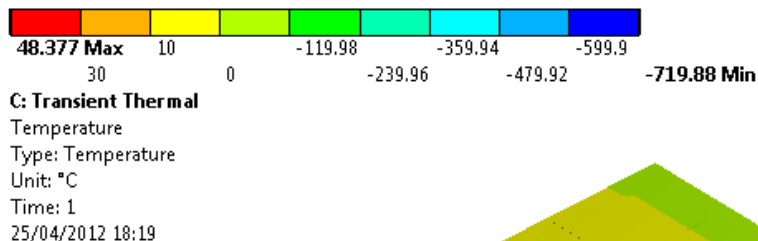
## Case 3

Half dump BOTTOM  
 view, T due to 1/4  
 Linac4 pulse (3)



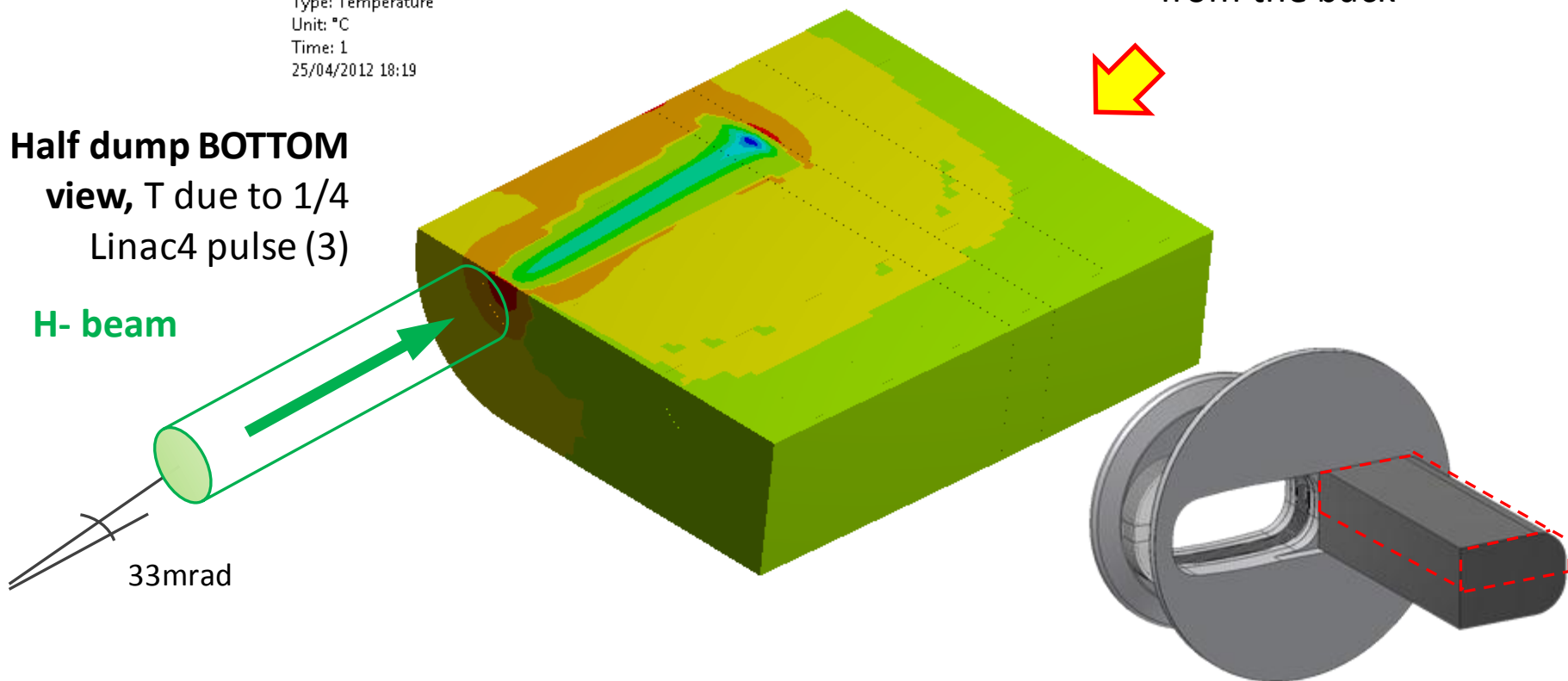
# Instantaneous eq. Stassi – SiC

## Case 3



Half dump BOTTOM  
view, T due to 1/4  
Linac4 pulse (3)

H- beam



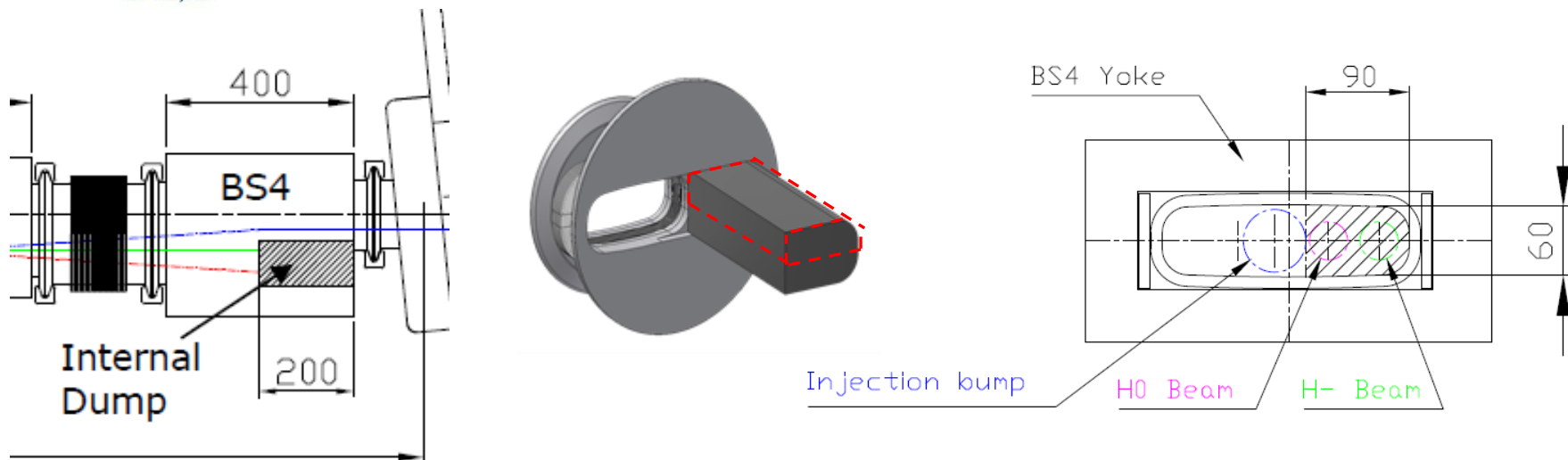
**Static Limit in tension:** 390 Mpa

**Static Limit in compression:** 3900 Mpa

**Safety factor** <sub>tension</sub>: 7.9

**Safety factor** <sub>compression</sub>: 5.1

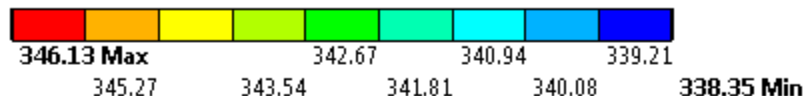
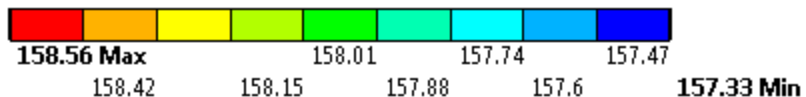
# Steady operation – SiC (1)



***In Steady State operation, if NO active cooling:***

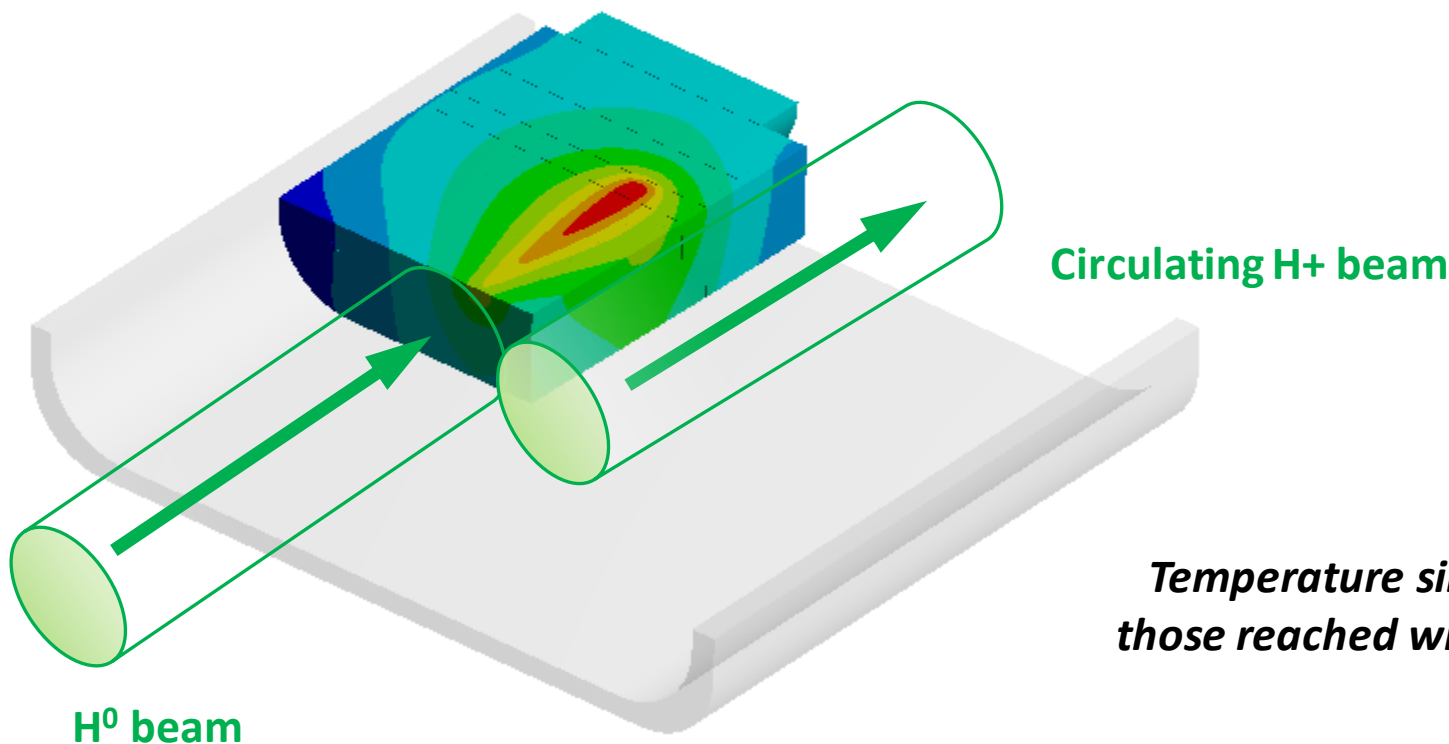
- inter radiation between external surface of dump core and internal surface of ceramic chamber → *considered in ANSYS simulation*
- inter radiation between external surface of ceramic chamber and internal surface of magnet → *considered as radiation with Ambient for chamber*
- conduction between dump/inserted piece and Stainless Steel connecting flange → *flange not considered for theses simulations*

# Steady operation – SiC (2)



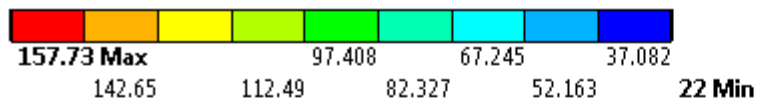
T: Steady-State Thermal, case 2 with radiation tot

Half dump BOTTOM view, T  
due to steady-state operation



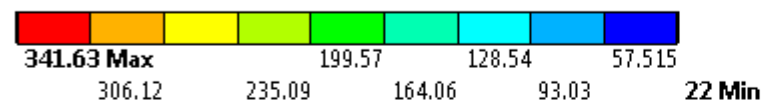
*Temperature similar to  
those reached with Al300.*

# Steady operation – SiC (3)



Case 1

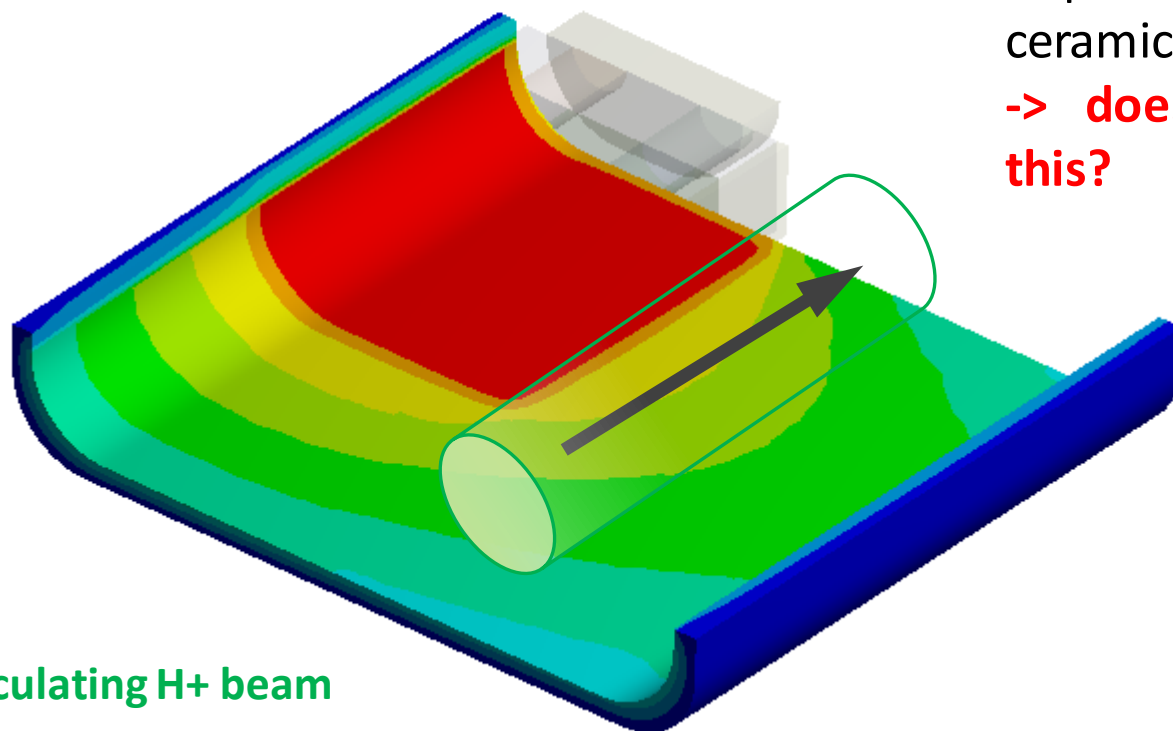
Half dump BOTTOM view, T  
due to steady-state operation



Case 2

T: Steady-State Thermal, case 2 with radiation tot

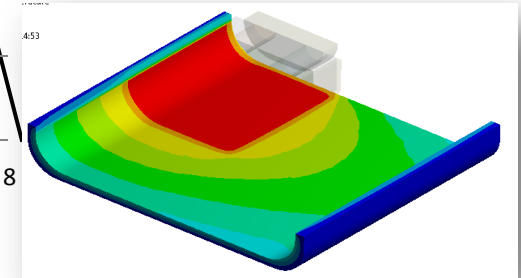
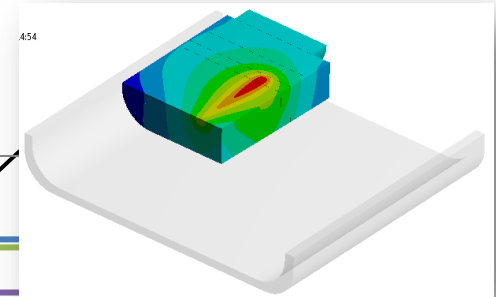
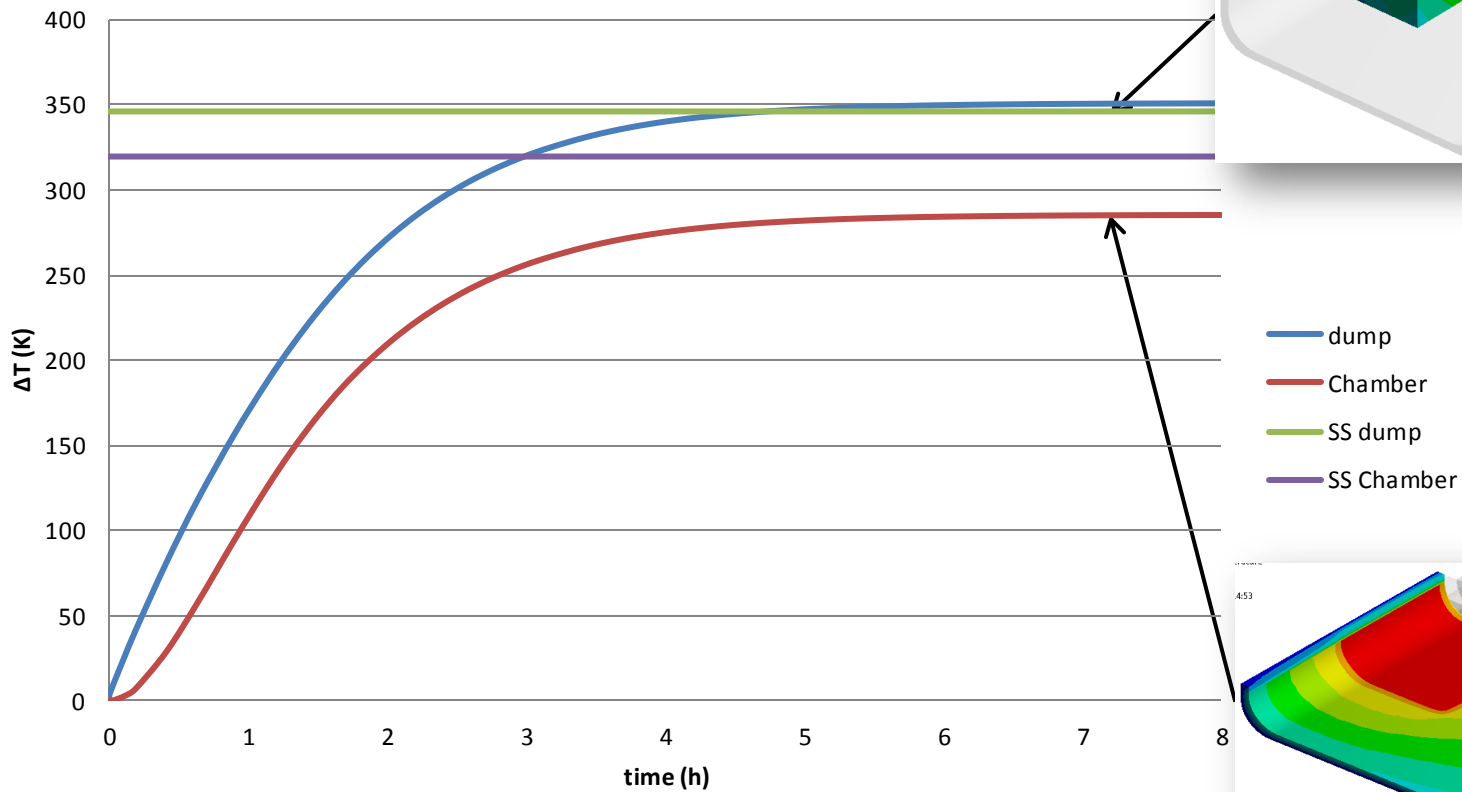
Important gradient of T on  
ceramic chamber  
-> **does the chamber allow  
this?**



Circulating H+ beam

# Transient to steady operation

## Case 2



# Does it need active cooling?

- Need to define the **maximum temperature** and **gradient of temperature** allowed on **ceramic chamber**
- Need to define the **maximum temperature** allowed on connecting **flange**

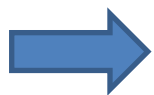
	Active cooling	NO Active cooling
Installation	X	✓
Steady State T	✓	X
Stresses	✓	X
Maintenance	X	✓
Activation water	X	✓
Complexity	X	✓

Bad on ceramic chamber and vacuum flange but acceptable for dump core itself.



# Conclusions

- An active cooling would significantly reduce the temperature field on dump core, ceramic chamber and connecting flange BUT
  - It requires a more complex geometry,
  - It requires a water flow -> water activation problem
  - More complicated for the maintenance



***Need to clearly assess the temperature limit on component closed to the dump core.***



# Thank You